

CO., LTD.

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Rev.A.1.1

|  |             |     |    |
|--|-------------|-----|----|
| Average gate power dissipation ( $T_j=125$ )                       | $P_{G(AV)}$ | 1   | W  |
| Peak gate power  | $P_{GM}$    | 10  | W  |
| Peak pulse voltage<br>( $T_j=25$ ; non-repetitive,off-state;FIG.7) | $V_{pp}$    | 0.7 | kV |

## ELECTRICAL CHARACTERISTICS

MARKING

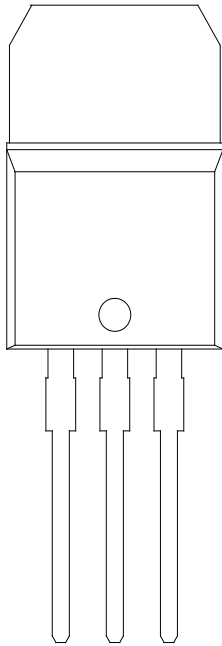


FIG.1: Maximum power dissipation versus RMS on-state current

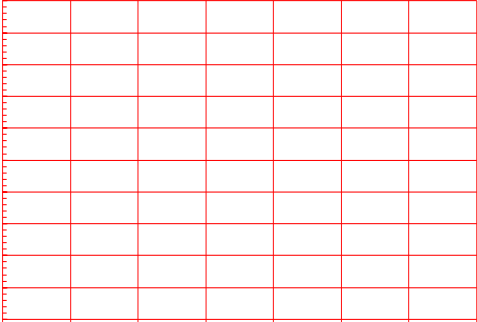
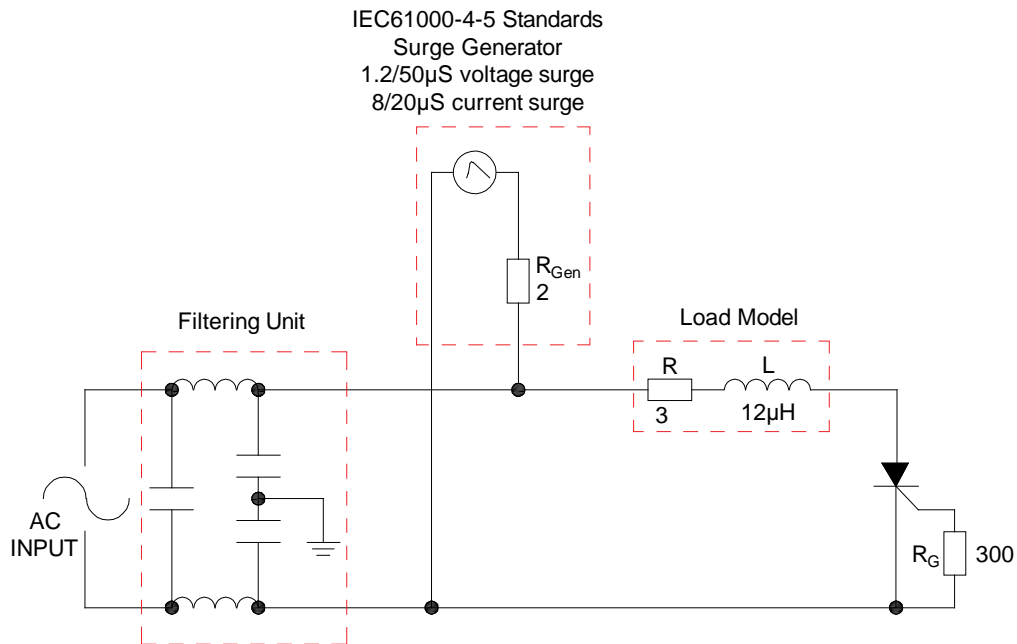


FIG.2: RMS on-state current versus case temperature

FIG.7 Test circuit for inductive and resistive loads to IEC-61000-4-5 standards.



## LEAD FORMING AND SOLDERING

Refer to the application note "Assembly Instructions for Thyristors in Through-hole Package" released by JieJie Microelectronics

BT151

JieJie M

PACKAGE MECHANICAL DATA

